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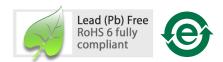


ADNS-6000

Laser Mouse Sensor



Data Sheet





Description

The Avago Technologies ADNS-6000 sensor along with the ADNS-6120 or ADNS-6130-001 lens, ADNS-6230-001 clip and ADNV-6340 laser diode form a complete and compact laser mouse tracking system. It is world's first laser-illuminated laser mouse navigation systems for corded applications. Enabled with Avago Technologies LaserStream, It can operate on many surface that prove difficult for traditional LED-based optical navigation. It's high-speed mouse motion - with velocity up to 20 inches per second and accelerations up to 8g.

There is no moving part in the complete assembly for ADNS-6000 laser mouse system, thus it is high reliability and less maintenance for the end user. In additional, precision optical alignment is not required, facilitating high volume assembly.

Theory of Operation

The ADNS-6000 is based on **LaserStream** Technology, which measures changes in position by optically acquiring sequential images (frames) and mathematically determining the direction and magnitude of movement.

ADNS-6000 contains an Image Acquisition System (IAS), a Digital Signal Processor (DSP), and a four wire serial port. The IAS acquires microscopic surface images via the lens and illumination system. These images are processed by the DSP to determine the direction and distance of motion. The DSP calculates the Δx and Δy relative displacement values. An external microcontroller reads the Δx and Δy information from the sensor serial port. The microcontroller then translates the data into PS2 or USB signals before sending them to the host PC or game console.

Applications

- Mice for game consoles and computer games
- Mice for desktop PC's, Workstations, and portable PC's
- Trackballs
- Integrated input devices

Features

- High speed motion detection up to 20 ips and 8g
- New LaserStream architecture for greatly improved optical navigation technology
- Programmable frame rate over 6400 frames per second
- SmartSpeed self-adjusting frame rate for optimum performance
- Serial port burst mode for fast data transfer
- 400 or 800 cpi selectable resolution
- Single 3.3 volt power supply
- Four-wire serial port along with Power Down, and Reset pins
- Laser fault detect circuitry on-chip for Eye Safety Compliance

Pinout

Pin	Name	Description
1	NCS	Chip select (active low input)
2	MISO	Serial data output (Master In/Slave Out)
3	SCLK	Serial clock input
4	MOSI	Serial data input (Master Out/Slave In)
5	NC	No Connection
6	RESET	Reset input
7	NPD	Power down (active low input)
8	OSC_OUT	Oscillator output
9	GUARD	Oscillator GND for PCB guard (optional)
10	OSC_IN	Oscillator input
11	REFC	Reference capacitor
12	REFB	Reference capacitor
13	RBIN	Set XY_LASER current
14	XY_LASER	LASER current output
15	NC	No Connection
16	VDD3	Supply voltage
17	GND	Ground
18	VDD3	Supply voltage
19	GND	Ground
20	LASER_NEN	Laser enable (active low)

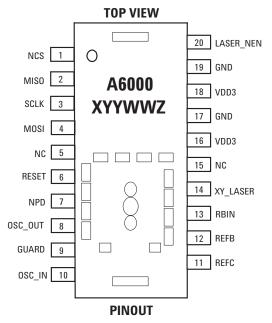


Figure 1. Package outline drawing (top view)

CAUTION: It is advised that normal static precautions be taken in handling and assembly of this component to prevent damage and/or degradation which may be induced by ESD

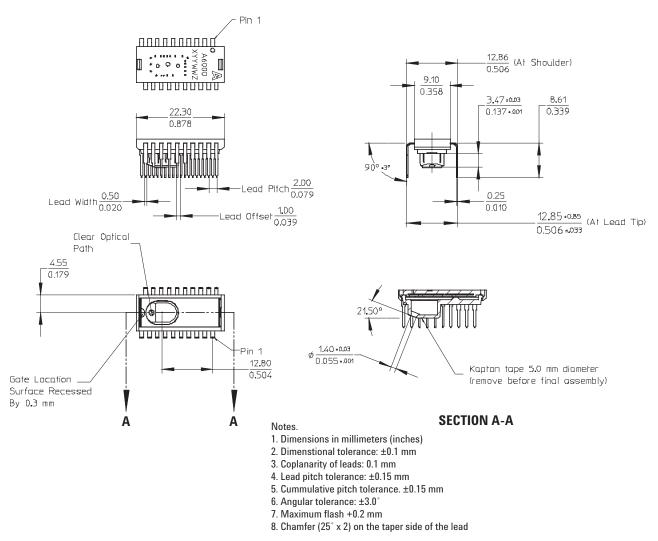
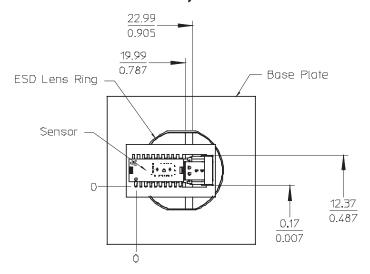
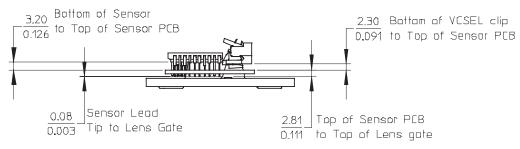


Figure 2. Package outline drawing

Overview of ADNS-6000 Laser Mouse Assembly





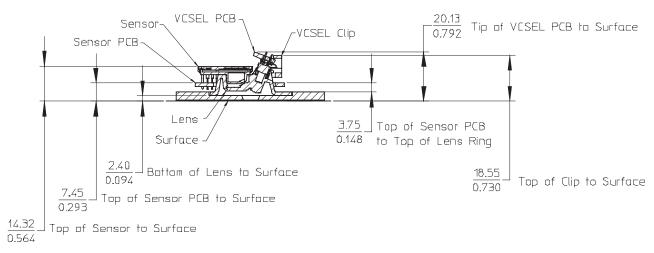
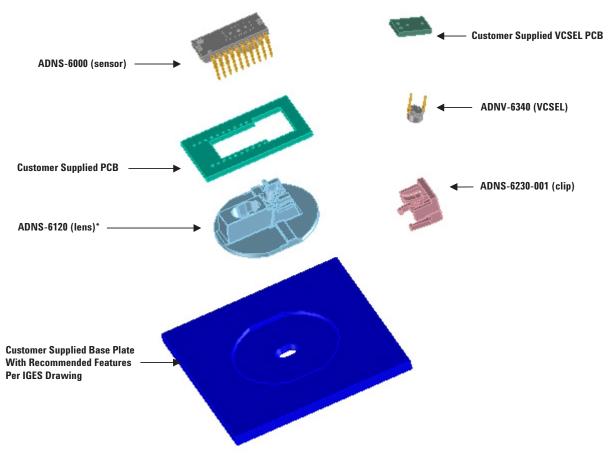


Figure 3. Assembly drawing of ADNS-6000 (top, front and cross-sectional view)

2D Assembly Drawing of ADNS-6000, PCBs and Base Plate



*or ADNS-6130-001 for trim lens

Figure 4. Exploded view drawing

Shown with ADNS-6120 Laser Mouse Lens, ADNS-6230-001 VCSEL Assembly Clip and ADNV-6340 VCSEL. The components interlock as they are mounted onto defined features on the base plate.

The ADNS-6000 laser mouse sensor is designed for mounting on a through hole PCB, looking down. There is an aperture stop and features on the package that align to the lens.

The ADNV-6340 VCSEL provides a laser diode with a single longitudinal and a single transverse mode. It is particularly suited as lower power consumption and highly coherent replacement of LEDs. It also provides wider operation range while still remaining within single-mode, reliable operating conditions.

The ADNS-6120 or ADNS-6130-001 Laser Mouse Lens is designed for use with ADNS-6000 sensor and the illumination subsystem provided by the VCSEL assembly clip

and the VCSEL. Together with the VCSEL, the ADNS-6120 or ADNS-6130-001 lens provides the directed illumination and optical imaging necessary for proper operation of the Laser Mouse Sensor. ADNS-6120 or ADNS-6130-001 is a precision molded optical component and should be handled with care to avoid scratching of the optical surfaces. ADNS-6120 has a large round flange to provide a long creepage path for any ESD events that occur at the opening of the base plate.

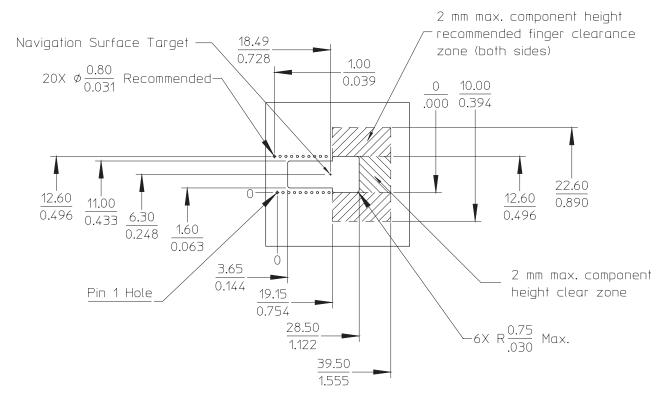
The ADNS-6230-001 VCSEL Assembly Clip is designed to provide mechanical coupling of the ADNV-6340 VCSEL to the ADNS-6120 or ADNS-6130-001 lens. This coupling is essential to achieve the proper illumination alignment required for the sensor to operate on a wide variety of surfaces.

Avago Technologies provides an IGES file drawing describing the base plate molding features for lens and PCB alignment.

Assembly Recommendation

- Insert the sensor and all other electrical components into the application PCB (main PCB board and VCSEL PCB board).
- 2. Wave solder the entire assembly in a no-wash solder process utilizing a solder fixture. The solder fixture is needed to protect the sensor during the solder process. It also sets the correct sensor-to -PCB distance, as the lead shoulders do not normally rest on the PCB surface. The fixture should be designed to expose the sensor leads to solder while shielding the optical aperture from direct solder contact.
- 3. Place the lens onto the base plate.
- 4. Remove the protective kapton tape from the optical aperture of the sensor. Care must be taken to keep contaminants from entering the aperture.
- 5. Insert the PCB assembly over the lens onto the base plate. The sensor aperture ring should self-align to the lens. The optical position reference for the PCB is set by the base plate and lens. Note that the PCB motion due to button presses must be minimized to maintain optical alignment.

- 6. Remove the protective kapton tape from the VCSEL.
- 7. Insert the VCSEL assembly into the lens.
- 8. Slide the clip in place until it latches. This locks the VCSEL and lens together.
- Tune the laser output power from the VCSEL to meet the Eye Safe Class I Standard as detailed in the LASER Power Adjustment Procedure.
- 10. Install the mouse top case. There must be a feature in the top case (or other area) to press down onto the sensor to ensure the sensor and lens are interlocked to the correct vertical height.



Dimensions in millimeters / inches

Figure 5. Recommended PCB mechanical cutouts and spacing

Design considerations for improving ESD Performance

For improved electrostatic discharge performance, typical creepage and clearance distance are shown in the table below. Assumption: base plate construction as per the Avago Technologies supplied IGES file for ADNS-6120 round lens.

The lens flange can be sealed (i.e. glued) to the base plate. Note that the lens material is polycarbonate and therefore, cyanoacrylate based adhesives or other adhesives that may damage the lens should **NOT** be used.

Typical Distance	Millimeters	
Creepage	12.0	
Clearance	2.1	

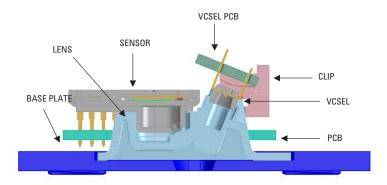


Figure 6. Cross section of PCB assembly

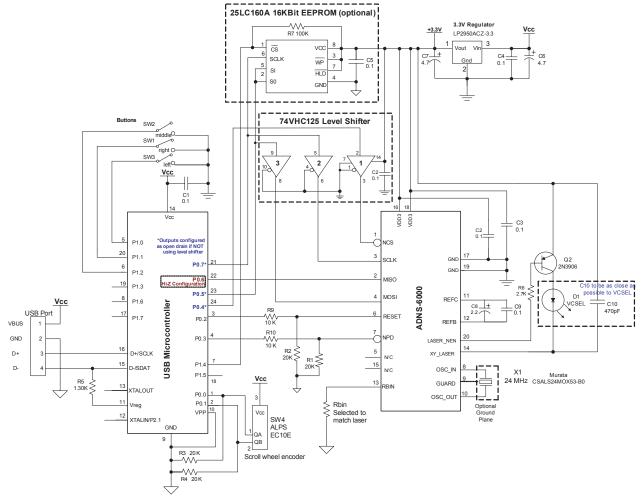


Figure 7. Schematic Diagram for 3-Button Scroll Wheel USB PS/2 Mouse

Notes (for figure 7)

- Caps for pins 11, 12, 16 and 18 MUST have trace lengths LESS than 5 mm on each side.
- Pins 16 and 18 caps MUST use pin 17 GND.
- Pin 9, if used, should not be connected to PCB GND to reduce potential RF emissions.
- The 0.1 uF caps must be ceramic.
- Caps should have less than 5 nH of self inductance.
- Caps should have less than 0.2 W ESR.
- NC pins should not be connected to any traces.
- Surface mount parts are recommended.
- Care must be taken when interfacing a 5V microcontroller to the ADNS-6000. Serial port inputs on the sensor should be connected to opendrain outputs from the microcontroller or use an active drive level shifter. NPD and RESET should be connected to 5V microcontroller outputs through a resistor divider or other level shifting technique.
- VDD3 and GND should have low impedance connections to the power supply.
- Because the RBIN pin sets the XY_LASER current, the following PC board layout practices should be followed to reduce the chance of uncontrolled laser drive current caused from a leakage path between RBIN and ground. One hypothetical source of such a leakage path is PC board contamination due to a liquid, such as a soft drink, being deposited on the printed circuit board.
- The RBIN resistor should be located close to the sensor pin 13. The traces between the resistor and the sensor should be short.
- The pin 13 solder pad and all exposed conductors connected to pin 13 should be surrounded by a guard trace connected to VDD3 and devoid of a solder mask.
- The pin 13 solder pad, the traces connected to pin 13, and the RBIN resistor should be covered with a conformal coating.
- The RBIN resistor should be a thru-hole style to increase the distance between its terminals. This does not apply if a conformal coating is used.

External PROM

The ADNS-6000 must operate from externally loaded programming. This architecture enables immediate adoption of new features and improved performance algorithms. The external program is supplied by Avago as a file, which may be burned into a programmable device. The example application shown in this document uses an EEPROM to store and load the external program memory. A micro-controller with sufficient memory may be used instead. On power-up and reset, the ADNS-6000 program is downloaded into volatile memory using the burst-mode procedure described in the Synchronous Serial Port section. The program size is 1986 x 8 bits.

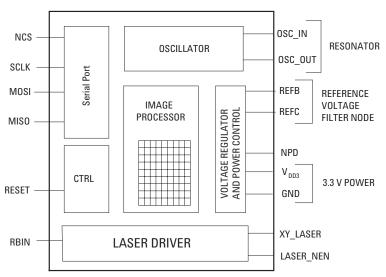


Figure 8. Block diagram of ADNS-6000 optical mouse sensor

LASER Drive Mode

The LASER has 2 modes of operation: DC and Shutter. In DC mode, the LASER is on at all times the chip is powered except when in the power down mode via the NPD pin. In shutter mode the LASER is on only during the portion of the frame that light is required. The LASER mode is set by the LASER_MODE bit in the Configuration_bits register. For optimum product lifetime, Avago Technologies recommends the default Shutter mode setting (except for calibration and test).

Laser Bin Table

Bin Number	Rbin Resistor Value (kohm)	Match_Bit (Reg 0x2C, Bit7)
2A	18.7	0
3A	12.7	0

Eye Safety

The ADNS-6000 and the associated components in the schematic of Figure 7 are intended to comply with Class 1 Eye Safety Requirements of IEC 60825-1. Avago Technologies suggests that manufacturers perform testing to verify eye safety on each mouse. It is also recommended to review possible single fault mechanisms beyond those described below in the section "Single Fault Detection".

Under normal conditions, the ADNS-6000 generates the drive current for the laser diode (ADNV-6340). In order to stay below the Class 1 power requirements, resistor Rbin must be set at least as high as the value in the bin table of Figure 7, based on the bin number of the laser diode and LP_CFG0 and LP_CFG1 must be programmed to appropriate values. Avago Technologies recommends using the exact Rbin value specified in the bin table to ensure sufficient laser power for navigation. The system comprised of the ADNS-6000 and ADNV-6340 is designed to maintain the output beam power within Class 1 requirements over component manufacturing tolerances and the recommended temperature range when adjusted per the procedure below and when implemented as shown in the recommended application circuit of Figure 7. For more information, please refer to Avago Technologies Laser Mouse Eye Safety Calculation Application Note 5088.

LASER Power Adjustment Procedure

- 1. The ambient temperature should be 25 °C \pm 5°C.
- 2. Set VDD3 to its permanent value.
- 3. Ensure that the laser drive is at 100% duty cycle.
- 4. Program the LP_CFG0 and LP_CFG1 registers to achieve an output power as close to 506uW as possible without exceeding it.

Good engineering practices should be used to guarantee performance, reliability and safety for the product design. Avago Technologies has additional information and detail, such as firmware practices, PCB layout suggestions, and manufacturing procedures and specifications that could be provided.

LASER Output Power

The laser beam output power as measured at the navigation surface plane is specified below. The following conditions apply:

- The system is adjusted according to the above procedure.
- 2. The system is operated within the recommended operating temperature range.
- 3. The VDD3 value is no greater than 50mV above its value at the time of adjustment.
- 4. No allowance for optical power meter accuracy is assumed.

Disabling the LASER

LASER_NEN is connected to the base of a PNP transistor which when ON connects V_{DD3} to the LASER. In normal operation, LASER_NEN is low. In the case of a fault condition (ground at XY_LASER or RBIN), LASER_NEN goes high to turn the transistor off and disconnect V_{DD3} from the LASER.

Laser Output Power

Parameter	Symbol	Minimum	Maximum	Units	Notes
Laser output power	LOP		716	uW	Per conditions above

Single Fault Detection

ADNS-6000 is able to detect a short circuit, or fault, condition at the RBIN and XY_LASER pins, which could lead to excessive laser power output. A low resistance path to ground on either of these pins will trigger the fault detection circuit, which will turn off the laser drive current source and set the LASER_NEN output high. When used in combination with external components as shown in the block diagram below, the system will prevent excess laser power for a single short to ground at RBIN or XY_LASER by shutting off the laser. Refer to the PC board layout notes for recommendations to reduce the chance of high resistance paths to ground existing due to PC board contamination.

In addition to the continuous fault detection described above, an additional test is executed automatically

whenever the LP_CFG0 register is written to. This test will check for a short to ground on the XY_LASER pin, a short to VDD3 on the XY_LASER pin, and will test the fault detection circuit on the XY_LASER pin.

Regulatory Requirements

- Passes FCC B and worldwide analogous emission limits when assembled into a mouse with shielded cable and following Avago recommendations.
- Passes IEC-1000-4-3 radiated susceptibility level when assembled into a mouse with shielded cable and following Avago Technologies's recommendations.
- Passes EN61000-4-4/IEC801-4EFT tests when assembled into a mouse with shielded cable and following Avago Technologies's recommendations.
- UL flammability level UL94 V-0.

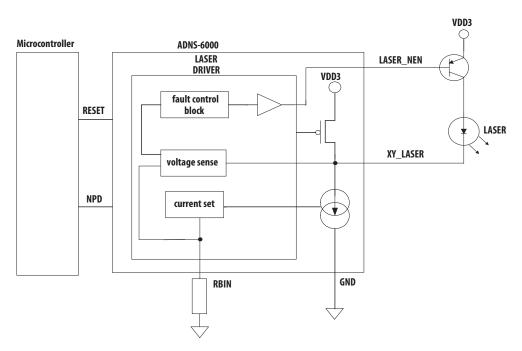


Figure 9. Single Fault Detection and Eye-safety Feature Block Diagram

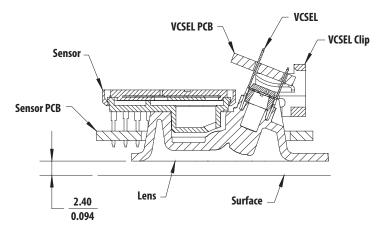


Figure 10. Distance from lens reference plane to surface

Absolute Maximum Ratings

Parameter	Symbol	Minimum	Maximum	Units	Notes
Storage Temperature	T _S	-40	85	°C	
Operating Temperature	T _A	-15	55	°C	
Lead Solder Temp			260	°C	For 10 seconds, 1.6mm below seating plane.
Supply Voltage	V _{DD3}	-0.5	3.7	V	
ESD			2	kV	All pins, human body model MIL 883 Method 3015
Input Voltage	V _{IN}	-0.5	V _{DD3} +0.5	V	NPD, NCS, MOSI, SCLK, RESET, OSC_IN, OSC_OUT, REFC, RBIN
Output current	lout		7	mA	MISO, LASER_NEN
Input Current	I _{IN}		15	mA	XY_LASER with RBIN 12.7kOhm LP_CFG0 = 0x00; LP_CFG1 = 0xFF

Recommended Operating Conditions

Parameter	Symbol	Minimum	Typical	Maximum	Units	Notes
Operating Temperature	T _A	0		40	°C	
Power supply voltage	V_{DD3}	3.10	3.30	3.60	Volts	
Power supply rise time	V _{RT}	1			us	0 to 3.0V
Supply noise (Sinusoidal)	V _{NB}			30 80	mV p-p	10kHz- 300KHZ 300KHz-50MHz
Oscillator Frequency	f _{CLK}	23	24	25	MHz	Set by ceramic resonator
Serial Port Clock Frequency	f _{SCLK}			2 500	MHz kHz	Active drive, 50% duty cycle Open drain drive with pull-ups on, 50 pF load
Resonator Impedance	X _{RES}			55	W	
Distance from lens reference plane to surface	Z	2.18	2.40	2.62	mm	Results in +/- 0.2 mm mini- mum DOF, see Figure 10
Speed	S			20	in/sec	
Acceleration	А	-8		8	g	
Frame Rate	FR	500		6469	Frames/s	See Frame_Period register section
Resistor value for LASER Drive Current set	R _{bin}	See Laser Bi	n Table		kOhms	ADNV-6340 VCSEL
Voltage at XY_LASER	V_{xy_laser}	0.7		V_{DD3}	V	

AC Electrical Specifications

Electrical Characteristics over recommended operating conditions. Typical values at 25 °C, V_{DD3}=3.3V, fclk=24MHz.

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read and subsequent commands SPI read address-data delay SPI motion read address-data delay From rising SCLK for for foot falling SCLK for for registers except Motor for segisters except Motor falling SCLK for for registers except Motor for falling SCLK for for foot falling SCLK for for foot falling SCLK for for foot falling SCLK for fall	or last bit of the first data byte, ast bit of the second address
delay to falling SCLK for fregisters except Mc SPI motion read address-data delay to falling SCLK for fregisters except Mc From rising SCLK for for for falling SCLK for for falling SCLK for for Applies to 0x02 Moregisters NCS to SCLK active to falling SCLK for for falling SCLK for for Applies to 0x02 Moregisters NCS to SCLK active to falling SCLK for for for falling SCLK for falling SCLK for for falling SCLK	or last bit of the first data byte, first bit of the second address
SPI motion read address-data delay to falling SCLK for falling SCLK for falling SCLK falling SCLK for falling SCLK falling SCLK for fal	or last bit of the address byte, first bit of data being read. All otion & Motion_Burst
SCLK to NCS inactive t _{SCLK-NCS} 120 ns From last SCLK fallis for valid MISO data NCS to MISO high-Z t _{NCS-MISO} 250 ns From NCS rising ed PROM download and frame capture t _{LOAD} 10 ms (See Figure 24 and	or last bit of the address byte, first bit of data being read. otion, and 0x50 Motion_Burst,
NCS to MISO high-Z t _{NCS-MISO} 120 ms for valid MISO data PROM download and frame capture t _{SCLK-NCS} 120 ms for valid MISO data ms (See Figure 24 and	dge to first SCLK rising edge
PROM download and frame capture 10 ms (See Figure 24 and	ng edge to NCS rising edge, transfer
frame capture t _{LOAD} 10 ms (See Figure 24 and	lge to MISO high-Z state
, , ,	25)
NCS to burst mode exit t_{BEXIT} 4 ms Time NCS must be	held high to exit burst mode
Transient Supply Current rent I _{DDT} 68 mA Max supply current to 3.6 V	t during a VDD3 ramp from 0
Input Capacitance C _{IN} 14-22 pF OSC_IN, OSC_OUT	

DC Electrical Specifications

Electrical Characteristics over recommended operating conditions. Typical values at 25 °C, V_{DD3}=3.3 V.

Parameter	Symbol	Minimum	Typical	Maximum	Units	Notes
DC Supply Current	I _{DD_AVG}			50	mA	DC average at 6469 fps. No DC load on XY_LASER, MISO.
Power Down Supply Current	I _{DDPD}		5	90	mA	NPD=GND; SCLK, MOSI, NCS=GND or V _{DD3} ; RESET=0V or GND
Input Low Voltage	V _{IL}			0.8	V	SCLK, MOSI, NPD, NCS, RESET
Input High Voltage	V _{IH}	0.7 * V _{DD3}			V	SCLK, MOSI, NPD, NCS, RESET
Input hysteresis	V _{I_HYS}		200		mV	SCLK, MOSI, NPD, NCS, RESET
Input current, pull-up disabled	I _{IH_DPU}		0	±10	mA	Vin=0.8*VDD3, SCLK, MOSI, NCS
Input current, CMOS inputs	I _{IH}		0	±10	mA	NPD, RESET, Vin=0.8*VDD3
Output current, pulled-up inputs	I _{OH_PU}	150	300	600	mA	Vin=0.2V, SCLK, MOSI, NCS; See bit 2 in Extended_Config register
XY_LASER Current	I _{LAS}		146/R _{bin}		A	$V_{xy_laser} >= 0.7 V$ $LP_CFG0 = 0x00, LP_CFG1 = 0xFF$
XY_LASER Current (fault mode)	I _{LAS}			500	uA	R_{bin} < 50 Ohms, or V_{XY_LASER} < 0.2 V
Output Low Voltage, MISO, LASER_NEN	V _{OL}			0.5	V	lout=2mA, MISO lout=1mA, LASER_NEN
Output High Voltage, MISO, LASER_NEN	V _{OH}	0.8*VDD3			V	lout=-2mA, MISO lout= -0.5 mA, LASER_NEN
XY_LASER Current (no Rbin)	I _{LAS_NRB}			1	mA	Rbin = open

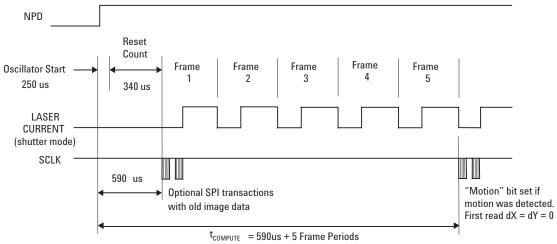


Figure 11. NPD Rising Edge Timing Detail

Typical Performance Characteristics

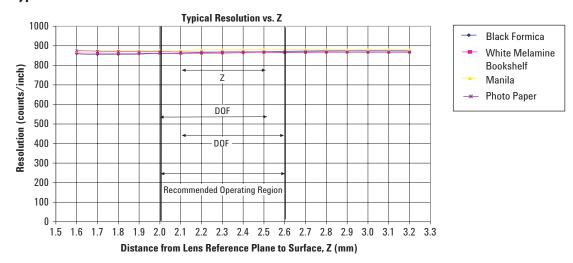
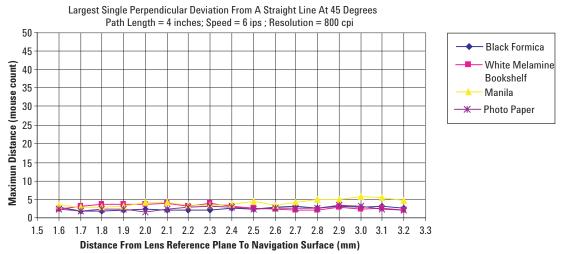


Figure 12. Mean Resolution vs. Z at 800cpi

Typical Path Deviation



Relationship of mouse count to distance = m (mouse count) / n (cpi) eg: Deviation of 7 mouse count = 7/800 = 0.00875 inch ~ 0.009 inch; where m = 7, n = 800 Figure 13. Average Error vs. Distance at 800cpi (mm)

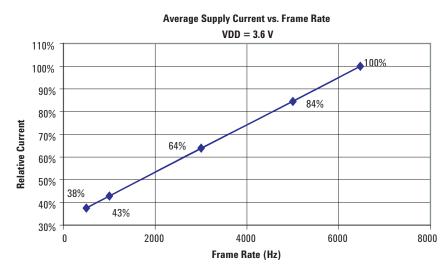


Figure 14. Average Supply Current vs. Frame Rate

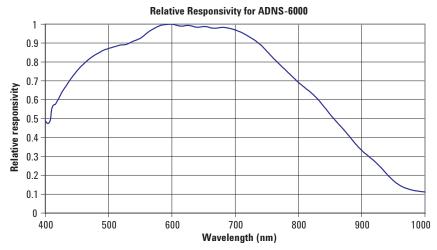


Figure 15. Relative Responsivity

Synchronous Serial Port

The synchronous serial port is used to set and read parameters in the ADNS-6000, and to read out the motion information. The serial port is also used to load PROM data into the ADNS-6000.

The port is a four wire port. The host micro-controller always initiates communication; the ADNS-6000 never initiates data transfers. The serial port cannot be activated while the chip is in power down mode (**NPD** low) or reset (**RESET** high). SCLK, MOSI, and NCS may be driven directly by a 3.3V output from a micro-controller, or they may be driven by an open drain configuration by enabling on-chip pull-up current sources. The open drain drive allows the use of a 5V micro-controller without any level shifting components. The port pins may be shared with other SPI slave devices. When the NCS pin is high, the inputs are ignored and the output is tri-stated.

The lines that comprise the SPI port are:

SCLK: Clock input. It is always generated by the master

(the micro-controller.)

MOSI: Input data. (Master Out/Slave In)

MISO: Output data. (Master In/Slave Out)

NCS: Chip select input (active low). NCS needs to be low to activate the serial port; otherwise, MISO

will be high Z, and MOSI & SCLK will be ignored. NCS can also be used to reset the serial port in

case of an error.

Chip Select Operation

The serial port is activated after NCS goes low. If NCS is raised during a transaction, the entire transaction is aborted and the serial port will be reset. This is true for all transactions including PROM download. After a transaction is aborted, the normal address-to-data or transaction-to-transaction delay is still required before beginning the next transaction. To improve communication reliability, all serial transactions should be framed by NCS. In other words, the port should not remain enabled during periods of non-use because ESD and EFT/B events could be interpreted as serial communication and put the chip into an unknown state. In addition, NCS must be raised after each burst-mode transaction is complete to terminate burst-mode. The port is not available for further use until burst-mode is terminated.

Write Operation

Write operation, defined as data going from the micro-controller to the ADNS-6000, is always initiated by the micro-controller and consists of two bytes. The first byte contains the address (seven bits) and has a "1" as its MSB to indicate data direction. The second byte contains the data. The ADNS-6000 reads MOSI on rising edges of **SCLK.**

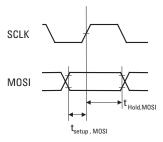


Figure 16. MOSI Setup and Hold Time

Read Operation

A read operation, defined as data going from the ADNS-6000 to the micro-controller, is always initiated by the micro-controller and consists of two bytes. The first byte contains the address, is sent by the micro-controller over **MOSI**, and has a "0" as its MSB to indicate data direction. The second byte contains the data and is driven by the ADNS-6000 over **MISO**. The sensor outputs **MISO** bits on falling edges of **SCLK** and samples **MOSI** bits on every rising edge of **SCLK**.

NOTE: The 250 ns minimum high state of SCLK is also the minimum MISO data hold time of the ADNS-6000. Since the falling edge of SCLK is actually the start of the next read or write command, the ADNS-6000 will hold the state of data on MISO until the falling edge of SCLK.

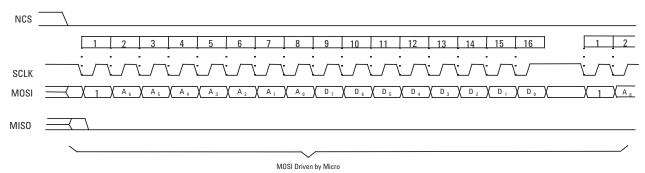
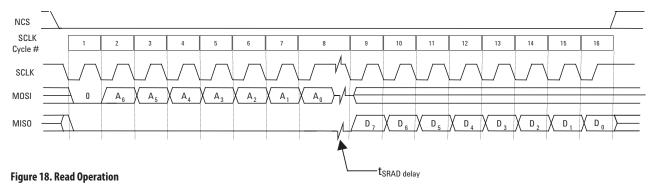


Figure 17. Write Operation



Required timing between Read and Write Commands (tsxx)

There are minimum timing requirements between read and write commands on the serial port.

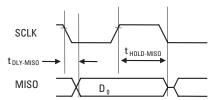


Figure 19. MISO Delay and Hold Time

If the rising edge of the SCLK for the last data bit of the second write command occurs before the 50 microsecond required delay, then the first write command may not complete correctly.

If the rising edge of SCLK for the last address bit of the read command occurs before the 50 microsecond required delay, the write command may not complete correctly.

The falling edge of SCLK for the first address bit of either the read or write command must be at least 250 ns after the last SCLK rising edge of the last data bit of the previous read operation. In addition, during a read operation SCLK should be delayed after the last address data bit to ensure that the ADNS-6000 has time to prepare the requested data.

Burst Mode Operation

Burst mode is a special serial port operation mode which may be used to reduce the serial transaction time for three predefined operations: motion read and PROM download and frame capture. The speed improvement is achieved by continuous data clocking to or from multiple registers without the need to specify the register address, and by not requiring the normal delay period between data bytes.

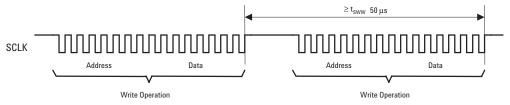


Figure 20. Timing between two write commands

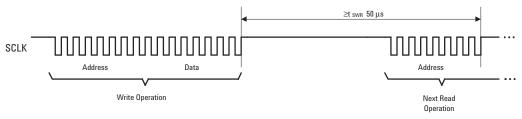


Figure 21. Timing between write and read commands

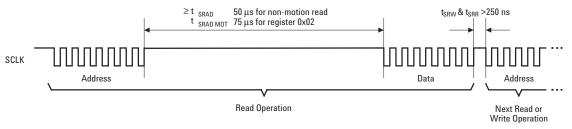


Figure 22. Timing between read and either write or subsequent read commands

Motion Read

Reading the Motion_Burst register activates this mode. The ADNS-6000 will respond with the contents of the Motion, Delta_X, Delta_Y, SQUAL, Shutter_Upper, Shutter_Lower, and Maximum_Pixel registers in that order. After sending the register address, the microcontroller must wait tsradomand and then begin reading data. All 64 data bits can be read with no delay between bytes by driving SCLK at the normal rate. The data are latched into the output buffer after the last address bit is received. After the burst transmission is complete, the micro-controller must raise the NCS line for at least tbruth to terminate burst mode. The serial port is not available for use until it is reset with NCS, even for a second burst transmission.

PROM Download

This function is used to load the Avago Technologiessupplied firmware file contents into the ADNS-6000. The firmware file is an ASCII text file with each 2-character byte on a single line.

The following steps activate this mode:

- 1. Perform hardware reset by toggling the RESET pin
- 2. Write 0x1D to register 0x14 (SROM_Enable register)
- 3. Wait at least 1 frame period
- 4. Write 0x18 to register 0x14 (SROM_Enable register)
- 5. Begin burst mode write of data file to register 0x60 (SROM_Load register)

After the first data byte is complete, the PROM or microcontroller must write subsequent bytes by presenting the data on the MOSI line and driving SCLK at the normal rate. A delay of at least t_{LOAD} must exist between data bytes as shown. After the download is complete, the micro-controller must raise the NCS line for at least t_{BEXIT} to terminate burst mode. The serial port is not available for use until it is reset with NCS, even for a second burst transmission.

Avago Technologies recommends reading the SROM_ID register to verify that the download was successful. In addition, a self-test may be executed, which performs a CRC on the SROM contents and reports the results in a register. The test is initiated by writing a particular value to the SROM_Enable register; the result is placed in the Data_Out register. See those register descriptions for more details.

Avago Technologies provides the data file for download; the file size is 1986 data bytes. The chip will ignore any additional bytes written to the SROM_Load register after the SROM file.

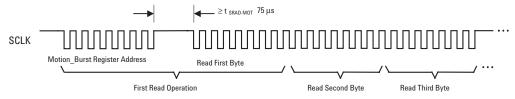


Figure 23. Motion burst timing.

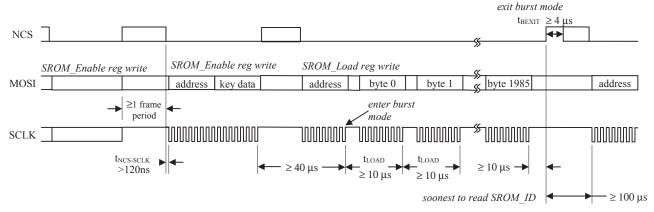


Figure 24. PROM Download Burst Mode

Frame Capture

This is a fast way to download a full array of pixel values from a single frame. This mode disables navigation and overwrites any downloaded firmware. A hardware reset is required to restore navigation, and the firmware must be reloaded.

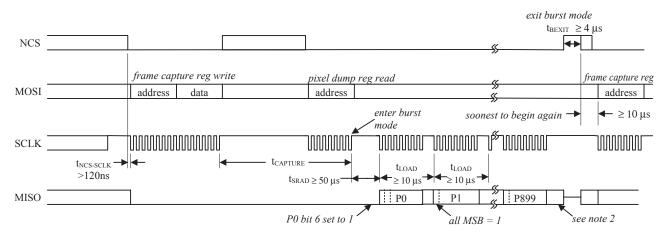
To trigger the capture, write to the Frame_Capture register. The next available complete 1 2/3 frames (1536 values) will be stored to memory. The data are retrieved by reading the Pixel_Burst register once using the normal read method, after which the remaining bytes are clocked out by driving SCLK at the normal rate. The byte time must be at least t_{LOAD}. If the Pixel_Burst register is read before the data is ready, it will return all zeros.

To read a single frame, read a total of 900 bytes. The next 636 bytes will be approximately 2/3 of the next frame.

The first pixel of the first frame (1st read) has bit 6 set to 1 as a start-of-frame marker. The first pixel of the second partial frame (901st read) will also have bit 6 set to 1. All other bytes have bit 6 set to zero. The MSB of all bytes is set to 1. If the Pixel_Burst register is read past the end of the data (1537 reads and on), the data returned will be zeros. Pixel data is in the lower six bits of each byte.

After the download is complete, the micro-controller must raise the NCS line for at least t_{BEXIT} to terminate burst mode. The read may be aborted at any time by raising NCS.

Alternatively, the frame data can also be read one byte at a time from the Frame_Capture register. See the register description for more information.



Notes:

- 1. MSB = 1 for all bytes. Bit 6 = 0 for all bytes except pixel 0 of both frames which has bit 6 = 1 for use as a frame marker.
- 2. Reading beyond pixel 899 will return the first pixel of the second partial frame.
- 3. $t_{CAPTURE} = 10 \text{ s} + 3 \text{ frame periods}.$
- 4. This figure illustrates reading a single complete frame of 900 pixels. An additional 636 pixels from the next frame are available.

Figure 25. Frame capture burst mode timing

The pixel output order as related to the surface is shown below.

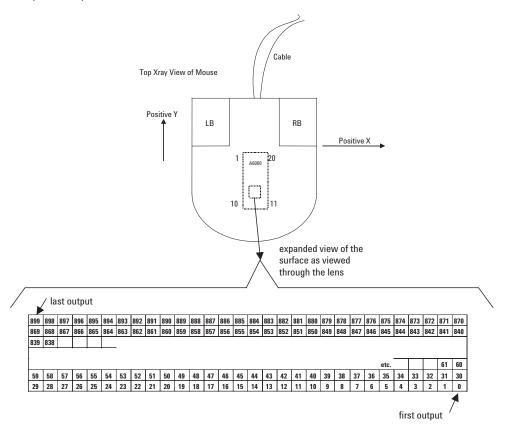


Figure 26. Pixel address map (surface referenced)

Error detection and recovery

- 1. The ADNS-6000 and the micro-controller might get out of synchronization due to ESD events, power supply droops or micro-controller firmware flaws. In such a case, the micro-controller should pulse NCS high for at least 1 μs. The ADNS-6000 will reset the serial port (but not the control registers) and will be prepared for the beginning of a new transmission after the normal transaction delay.
- 2. Invalid addresses: Writing to an invalid address will have no effect. Reading from an invalid address will return all zeros.
- 3. Termination of a transmission by the micro-controller may sometimes be required (for example, due to a USB suspend interrupt during a read operation). To accomplish this the micro-controller should raise NCS. The ADNS-6000 will not write to any register and will reset the serial port (but not the control registers) and be prepared for the beginning of future transmissions after NCS goes low. The normal delays between reads or writes (t_{SWW}, t_{SWr}, t_{SRAD}, t_{SRAD-mot}) are still required after aborted transmissions.

- 4. The micro-controller can verify success of write operations by issuing a read command to the same address and comparing written data to read data.
- 5. The micro-controller can verify the synchronization of the serial port by periodically reading the product ID and inverse product ID registers.
- 6. The microcontroller can read the SROM_ID register to verify that the sensor is running downloaded PROM code. ESD or similar noise events may cause the sensor to revert to native ROM execution. If this should happen, pulse RESET and reload the SROM code.

Notes on Power-up and the serial port

Reset Circuit

The ADNS-6000 does not perform an internal power up self-reset; the reset pin must be raised and lowered to reset the chip. This should be done every time power is applied. During power-up there will be a period of time after the power supply is high but before any clocks are available. The table below shows the state of the various pins during power-up and reset when the RESET pin is driven high by a micro-controller.

State of Signal Pins After VDD is Valid						
Pin	Before Reset	During Reset	After Reset			
SPI pullups	undefined	off	on (default)			
NCS	hi-Z control functional	hi-Z control functional	functional			
MISO	driven or hi-Z (per NCS)	driven or hi-Z (per NCS)	low or hi-Z (per NCS)			
SCLK	undefined	ignored	functional			
MOSI	undefined	ignored	functional			
XY_LASER	undefined	hi-Z	functional			
RESET	functional	high (externally driven)	functional			
NPD	undefined	ignored	functional			
LASER_NEN	undefined	high (off)	functional			

Power Down Circuit

The following table lists the pin states during power down

The chip is put into the power down (PD) mode by lowering the NPD input. When in PD mode, the oscillator is stopped but all register contents are retained. To achieve the lowest current state, all inputs must be held externally within 200mV of a rail, either ground or VDD3. The chip outputs are driven low or hi-Z during PD to prevent current consumption by an external load.

State of Signal Pins During Power Down					
Pin	NPD low	After wake from PD			
SPI pullups	off	pre-PD state			
NCS	hi-Z control functional	functional			
MISO	low or hi-Z (per NCS)	pre-PD state or hi-Z			
SCLK	ignored	functional			
MOSI	ignored	functional			
XY_LASER	high (off)	functional			
RESET	functional	functional			
NPD	low (driven externally)	functional			
REFC	V _{DD3}	REFC			
OSC_IN	low	OSC_IN			
OSC_OUT	high	OSC_OUT			
LASER_NEN	high (off)	functional			

Registers

The ADNS-6000 registers are accessible via the serial port. The registers are used to read motion data and status as well as to set the device configuration.

0x00 Product_ID R 0x01 Revision_ID R 0x02 Motion R 0x03 Delta_X R 0x04 Delta_Y R 0x05 SQUAL R 0x06 Pixel_Sum R 0x07 Maximum_Pixel R 0x08 Reserved R 0x09 Reserved R/W 0x0a Configuration_bits R/W 0x0b Extended_Config R/W 0x0c Data_Out_Lower R 0x0d Data_Out_Upper R 0x0e Shutter_Lower R 0x0f Shutter_Upper R 0x10 Frame_Period_Lower R 0x11 Frame_Period_Upper R	0x1C 0x20 0x20 0x00
0x02 Motion R 0x03 Delta_X R 0x04 Delta_Y R 0x05 SQUAL R 0x06 Pixel_Sum R 0x07 Maximum_Pixel R 0x08 Reserved 0x09 Reserved 0x00 Configuration_bits R/W 0x0a Configuration_bits R/W 0x0b Extended_Config R/W 0x0c Data_Out_Lower R 0x0d Data_Out_Upper R 0x0e Shutter_Lower R 0x0f Shutter_Upper R 0x10 Frame_Period_Lower R	0x20
0x03 Delta_X R 0x04 Delta_Y R 0x05 SQUAL R 0x06 Pixel_Sum R 0x07 Maximum_Pixel R 0x08 Reserved 0x09 Reserved 0x0a Configuration_bits R/W 0x0b Extended_Config R/W 0x0c Data_Out_Lower R 0x0d Data_Out_Upper R 0x0e Shutter_Lower R 0x0f Shutter_Upper R 0x10 Frame_Period_Lower R	
0x04 Delta_Y R 0x05 SQUAL R 0x06 Pixel_Sum R 0x07 Maximum_Pixel R 0x08 Reserved 0x09 Reserved 0x0a Configuration_bits R/W 0x0b Extended_Config R/W 0x0c Data_Out_Lower R 0x0d Data_Out_Upper R 0x0e Shutter_Lower R 0x0f Shutter_Upper R 0x10 Frame_Period_Lower R	0x00
0x05 SQUAL R 0x06 Pixel_Sum R 0x07 Maximum_Pixel R 0x08 Reserved 0x09 Reserved 0x0a Configuration_bits R/W 0x0b Extended_Config R/W 0x0c Data_Out_Lower R 0x0d Data_Out_Upper R 0x0e Shutter_Lower R 0x0f Shutter_Upper R 0x10 Frame_Period_Lower R	0,000
0x06 Pixel_Sum R 0x07 Maximum_Pixel R 0x08 Reserved 0x09 Reserved 0x0a Configuration_bits R/W 0x0b Extended_Config R/W 0x0c Data_Out_Lower R 0x0d Data_Out_Upper R 0x0e Shutter_Lower R 0x0f Shutter_Upper R 0x10 Frame_Period_Lower R	0x00
0x07 Maximum_Pixel R 0x08 Reserved 0x09 Reserved 0x0a Configuration_bits R/W 0x0b Extended_Config R/W 0x0c Data_Out_Lower R 0x0d Data_Out_Upper R 0x0e Shutter_Lower R 0x0f Shutter_Upper R 0x10 Frame_Period_Lower R	0x00
0x08 Reserved 0x09 Reserved 0x0a Configuration_bits R/W 0x0b Extended_Config R/W 0x0c Data_Out_Lower R 0x0d Data_Out_Upper R 0x0e Shutter_Lower R 0x0f Shutter_Upper R 0x10 Frame_Period_Lower R	0x00
0x09 Reserved 0x0a Configuration_bits R/W 0x0b Extended_Config R/W 0x0c Data_Out_Lower R 0x0d Data_Out_Upper R 0x0e Shutter_Lower R 0x0f Shutter_Upper R 0x10 Frame_Period_Lower R	0x00
0x0a Configuration_bits R/W 0x0b Extended_Config R/W 0x0c Data_Out_Lower R 0x0d Data_Out_Upper R 0x0e Shutter_Lower R 0x0f Shutter_Upper R 0x10 Frame_Period_Lower R	
0x0b Extended_Config R/W 0x0c Data_Out_Lower R 0x0d Data_Out_Upper R 0x0e Shutter_Lower R 0x0f Shutter_Upper R 0x10 Frame_Period_Lower R	
0x0c Data_Out_Lower R 0x0d Data_Out_Upper R 0x0e Shutter_Lower R 0x0f Shutter_Upper R 0x10 Frame_Period_Lower R	0x49
0x0d Data_Out_Upper R 0x0e Shutter_Lower R 0x0f Shutter_Upper R 0x10 Frame_Period_Lower R	0x08
0x0e Shutter_Lower R 0x0f Shutter_Upper R 0x10 Frame_Period_Lower R	Any
0x0f Shutter_Upper R 0x10 Frame_Period_Lower R	Any
0x10 Frame_Period_Lower R	0x85
	0x00
0x11 Frame_Period_Upper R	Any
	Any
0x12 Motion_Clear W	Any
0x13 Frame_Capture R/W	0x00
0x14 SROM_Enable W	0x00
0x15 Reserved	
0x16 Configuration II R/W	0x34
0x17 Reserved	
0x18 Reserved	
0x19 Frame_Period_Max_Bound Lower R/W	0x90
0x1a Frame_Period_Max_Bound_Upper R/W	0x65
0x1b Frame_Period_Min_Bound_Lower R/W	0x7E
0x1c Frame_Period_Min_Bound_Upper R/W	0x0E
0x1d Shutter_Max_Bound_Lower R/W	0x20
0x1e Shutter_Max_Bound_Upper R/W	0x4E
0x1f SROM_ID R	Version dependent
0x20-0x2b Reserved	
0x2c LP_CFG0 R/W	0x7F
0x2d LP_CFG1 R/W	0x80
0x2e-0x3c Reserved	
0x3d Observation R/W	0x00
0x3e Reserved	
0x3f Inverse Product ID R	
0x40 Pixel_Burst R	0xE3
0x50 Motion_Burst R	0xE3 0x00
0x60 SROM_Load W	

Product_I	D		Address:	Address: 0x00				
Access: Re	ad		Default V	Default Value: 0x1C				
Bit	7	6	5	4	3	2	1	0
Field	PID ₇	PID ₆	PID ₅	PID ₄	PID ₃	PID ₂	PID ₁	PID ₀

Data Type: 8-Bit unsigned integer

USAGE: This register contains a unique identification assigned to the ADNS-6000. The value in this register does not change; it can be used to verify that the serial communications link is functional.

Revision_ID			Address:	Address: 0x01						
Access: Read			Default V	Default Value: 0x20						
Bit	7	6	5	4	3	2	1	0		
Field	RID ₇	RID ₆	RID ₅	RID ₄	RID ₃	RID ₂	RID ₁	RID ₀		

Data Type: 8-Bit unsigned integer.

USAGE: This register contains the IC revision. It is subject to change when new IC versions are released.

NOTE: The downloaded SROM firmware revision is a separate value and is available in the SROM_ID register.

Motion			Address:	Address: 0x02						
Access: Read			Default V	Default Value: 0x00						
Bit	7	6	5	4	3	2	1	0		
Field	MOT	Reserved	LP_Valid	OVF	Reserved	Reserved	Fault	RES		

Data Type: Bit field.

USAGE: Register 0x02 allows the user to determine if motion has occurred since the last time it was read. If so, then the user should read registers 0x03 and 0x04 to get the accumulated motion. It also tells if the motion buffers have overflowed, if fault is detected, and the current resolution setting.

Field Name	Description
MOT	Motion since last report 0 = No motion 1 = Motion assured data ready for reading in Dolta, V and Dolta, V registers
LP_Valid	1 = Motion occurred, data ready for reading in Delta_X and Delta_Y registers This bit is an indicator of complementary value contained in registers 0x2C and 0x2D. 0 = register 0x2C and 0x2D do not have complementary values 1 = register 0x2C and 0x2D contain complementary values
OVF	Motion overflow, DY and/or DX buffer has overflowed since last report 0 = no overflow 1 = overflow has occurred
Fault	Indicates that the RBIN and/or XY_LASER pin is shorted to GND. 0 = no fault detected 1 = fault detected
RES	Resolution in counts per inch (cpi). Resolution values are approximate. 0 = 400 1 = 800

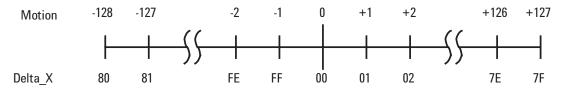
Notes for Motion:

- 1. Reading this register freezes the Delta_X and Delta_Y register values. Read this register before reading the Delta_X and Delta_Y registers. If Delta_X and Delta_Y are not read before the motion register is read a second time, the data in Delta_X and Delta_Y will be lost.
- 2. Avago Technologies RECOMMENDS that registers 0x02, 0x03 and 0x04 be read sequentially. See Motion burst mode also.
- 3. Internal buffers can accumulate more than eight bits of motion for X or Y. If either one of the internal buffers overflows, then absolute path data is lost and the OVF bit is set. This bit is cleared once some motion has been read from the Delta_X and Delta_Y registers, and if the buffers are not at full scale. Since more data is present in the buffers, the cycle of reading the Motion, Delta_X and Delta_Y registers should be repeated until the motion bit (MOT) is cleared. Until MOT is cleared, either the Delta_X or Delta_Y registers will read either positive or negative full scale. If the motion register has not been read for long time, at 400 cpi it may take up to 16 read cycles to clear the buffers, at 800 cpi, up to 32 cycles. Alternatively, writing to the Motion_Clear register (register 0x12) will clear all stored motion at once.

Delta_X			Address:	Address: 0x03						
Access: Re	ead		Default \	Default Value: 0x00						
Bit	7	6	5	4	3	2	1	0		
Field	X ₇	X ₆	X ₅	X ₄	X ₃	X ₂	X ₁	X ₀		

Data Type: Eight bit 2's complement number.

USAGE: X movement is counts since last report. Absolute value is determined by resolution. Reading clears the register.



Delta_Y			Address:	Address: 0x04						
Access: Read			Default \	Default Value: 0x00						
Bit	7	6	5	4	3	2	1	0		
Field	Y ₇	Y ₆	Y ₅	Y ₄	Y ₃	Y ₂	Y ₁	Y ₀		

Data Type: Eight bit 2's complement number.

USAGE: Y movement is counts since last report. Absolute value is determined by resolution. Reading clears the register.

